



Material Content Data Sheet



Sales Product Name		IPD60R180P7S		Issued		25. January 2018		
MA#		MA001994456						
Package		PG-TO252-3-344		Weight*		323.73 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.174	1.29	1.29	12894	12894
leadframe	inorganic material	phosphorus	7723-14-0	0.043	0.01		134	
	non noble metal	iron	7439-89-6	0.144	0.04		445	
	non noble metal	copper	7440-50-8	143.904	44.47	44.52	444514	445093
	non noble metal	aluminium	7429-90-5	0.427	0.13	0.13	1318	1318
wire	non noble metal	aluminium	7429-90-5	0.427	0.13	0.13	1318	1318
encapsulation	organic material	carbon black	1333-86-4	0.673	0.21		2079	
	plastics	epoxy resin	-	18.176	5.61		56144	
	inorganic material	silicondioxide	60676-86-0	115.785	35.77	41.59	357657	415880
leadfinish	non noble metal	tin	7440-31-5	3.834	1.18	1.18	11842	11842
solder	non noble metal	tin	7440-31-5	0.071	0.02		218	
	noble metal	silver	7440-22-4	0.088	0.03		273	
	non noble metal	lead	7439-92-1	3.376	1.04	1.09	10430	10921
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		31	
	non noble metal	iron	7439-89-6	0.033	0.01		102	
	non noble metal	copper	7440-50-8	32.995	10.19	10.20	101919	102052
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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